COM'L: -15/25

MIL: -20

# 口

# PALCE610H-15/25

## Advanced Micro Devices

# **EE CMOS High Performance Programmable Array Logic**

#### DISTINCTIVE CHARACTERISTICS

- AMD's Programmable Array Logic (PAL®) architecture
- Electrically-erasable CMOS technology providing half power (90 mA lcc) at high speed -15 = 15 ns tpp
  - -25 = 25 ns tpp
- Sixteen macrocells with configurable I/O architecture
- Registered or combinatorial operation
- Registers programmable as D, T, J-K, or S-R

- Asynchronous clocking via product term or bank register clocking from external pins
- Register preload for testability
- **■** Power-up reset for initialization
- Space-saving 24-pin SKINNYDIP® and 28-pin PLCC packages
- Fully tested for 100% programming yield and high reliability
- Supported by popular industry-standard design software

#### **GENERAL DESCRIPTION**

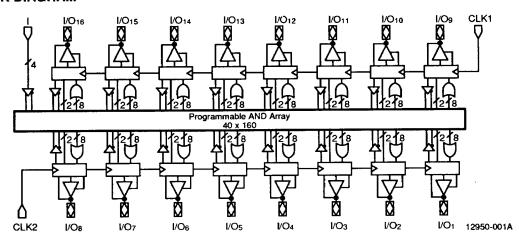
The PALCE610 is a general purpose PAL device and is functionally and fuse map equivalent to the EP610. It can accommodate logic functions with up to 20 inputs and 16 outputs. There are 16 I/O macrocells that can be individually configured to the user's specifications. The macrocells can be configured as either registered or combinatorial. The registers can be configured as D, T, J–K, or S–R flip-flops.

The PALCE610 uses the familiar sum-of-products logic with programmable-AND and fixed-OR structure. Eight product terms are brought to each macrocell to provide logic implementations.

The PALCE610 is manufactured using advanced CMOS EE technology providing high density and low power consumption. Moreover, it is a high-speed device having a worst-case too of 15 ns. Space-saving 24-pin SKINNYDIP and 28-pin PLCC packages are offered.

This device can be quickly erased and reprogrammed providing for easy prototyping. Once a device is programmed the security bit can be used to provide protection from copying a proprietary design.

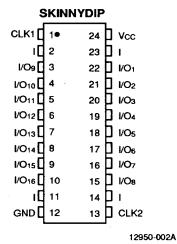
#### **BLOCK DIAGRAM**

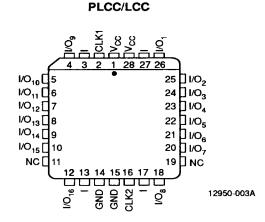


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Publication # 12950 Rev. D Amendment /0 Issue Date: July 1991

# CONNECTION DIAGRAMS Top View





Note:

Pin 1 is marked for orientation

#### **PIN DESIGNATIONS**

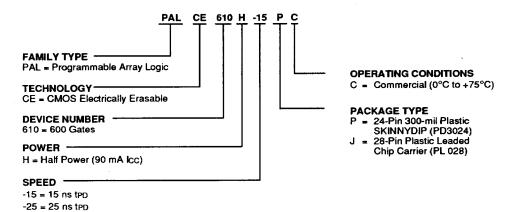
CLK Clock
GND Ground
I Input
I/O Input/Output
NC No Connect
Vcc Supply Voltage



# ORDERING INFORMATION Commercial Products

AMD programmable logic products for commercial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of: Family Type

ramily Type
Technology
Device Number
Power
Speed
Package Type
Operating Conditions



Valid Combinations		
PALCE610H-15	50.10	
PALCE610H-25	PC, JC	

#### Valid Combinations

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, and to check on newly released combinations.

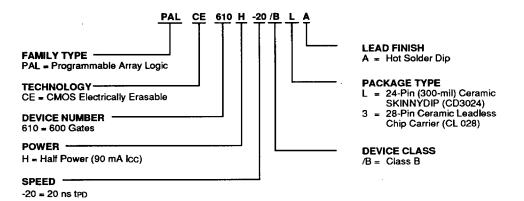
Note: Marked with AMD logo.

# ORDERING INFORMATION APL Products

AMD programmable logic products for Aerospace and Defense applications are available with several ordering options. APL (Approved Products List) products are fully compliant with MIL-STD-883 requirements. The order number (Valid Combination) is formed by a combination of:

Family Type

Technology
Device Number
Power
Speed
Package Type
Operating Conditions



Valid Combinations			
PALCE610H-20	/BLA,/B3A		

#### Valid Combinations

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, and to check on newly released combinations.

Note: Marked with AMD logo.

#### **Group A Tests**

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

#### Military Burn-in

Military burn-in is in accordance with the current revision of MIL-STD-883, Test Method 1015, Conditions A through E. Test conditions are selected at AMD's option.



#### **FUNCTIONAL DESCRIPTION**

The PALCE610 is a general purpose programmable logic device. It has 16 independently-configurable macrocells. Each macrocell can be configured as either combinatorial or registered. The registers can be D, T, J–K, or S–R type flip-flops. The device has 4 dedicated input pins and 2 clock pins. Each clock pin controls 8 of the 16 macrocells.

The programming matrix implements a programmable AND logic array which drives a fixed OR logic array. Buffers for device inputs have complementary outputs to provide user-programmable input polarity. Unused input pins should be tied to Vcc or ground.

The array uses AMD's electrically erasable technology. An unprogrammed bit is disconnected and a programmed bit is connected. Product terms with all bits unprogrammed assume the logical-HIGH state and product terms with both the TRUE and Complement bits programmed assume the logical-LOW state.

The programmable functions in the PALCE610 are automatically configured from the user's design specifications, which can be in a number of formats. The design specification is processed by development software to verify the design and create a programming file. This file, once downloaded to the programmer, configures the design according to the user's desired function.

## **Macrocell Configurations**

The PALCE610 macrocell can be configured as either combinatorial or registered. Both the combinatorial and registered configurations have output polarity control. The register can be configured as a D, T, J–K, or S–R type flip-flop. Figure 1 shows the possible configurations.

Each macrocell can select as its clock either the corresponding clock pin or the CLK/OE product term. If the clock pin is selected, the output enable is controlled by the CLK/OE product term. If the CLK/OE product term is selected, the output is always enabled.

#### Combinatorial I/O

All 8 product terms are available to the OR gate. The output-enable function is performed by the CLK/OE product term.

#### **Registered Configurations**

There are 4 flip-flop types available: D, T, J-K and S-R.

The registers can be configured as synchronous or asynchronous. In the synchronous configuration, the clock is controlled by the clock input pin. The output enable is controlled by the product term function. In the asynchronous configuration, the clock input is controlled by the product term. The output is always enabled.

In The D and T configurations, feedback can be either from Q or the output pin. This allows D and T configurations to be either outputs or I/O. In the J–K and S–R configurations, feedback is only from Q; therefore, J–K and S–R configurations are strictly outputs.

## D Flip-Flop

All 8 product terms are available to the OR gate. The D input polarity is controlled by an exclusive-OR gate. For the D flip-flop, the output level is the D-input level at the rising edge of the clock.

Е	D	Qn	Qn+1
Γ	0	0	0
İ	0	1	0
l	1	0	1
	1	1	1

#### T Flip-Flop

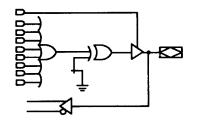
All 8 product terms are available to the OR gate. The T input polarity is controlled by an exclusive-OR gate. For the T register, the output level toggles when the T input is HIGH and remains the same when the T input is LOW.

T	Qn	Qn+1
0	0	0
0	1	1
1	0	1
1	1	0

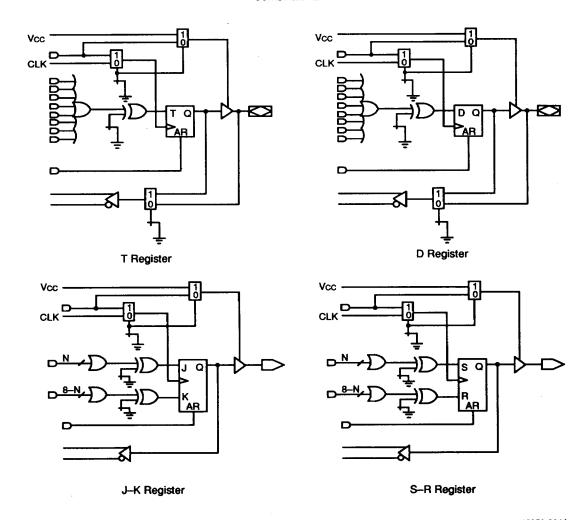
## J-K Flip-Flop

The 8 product terms are divided between the J and K inputs. N product terms go to the J input and 8-N product terms go to the K input, where N can range from 0 to 8. Both the J and K inputs to the flip-flop have polarity control via exclusive-OR gates. The J-K flip-flop operation is shown below.

J	K	Qn	Qn+1
0	0	0	0
0	0	1	1
0	1	0	0
0	1	1	0
1	0	0	1
1	0	1	1
1	1	0	1
1	1	1	0



#### Combinatorial



12950-004A

Figure 1. Macrocell Configurations



## S-R Flip-Flop

The 8 product terms are divided between the S and R inputs. N product terms go to the S input and 8-N product terms go to the R input, where N can range from 0 to 8. Both the S and R inputs to the flip-flop have polarity control via exclusive-OR gates. The S-R flip-flop operation is shown below.

S	R	Qn	Qn+1		
0	0	0	0		
0	0	1	1		
0	1	0	0		
0	1	1	0		
1	0	0	1		
1	0	1	1		
1	1	Not Allowed			

## **Asynchronous Reset**

All flip-flops have an asynchronous-reset product-term input. When the product term is true, the flip-flop will reset to a logic LOW, regardless of the clock and data inputs.

## **Power-Up Reset**

All flip-flops power up to a logic LOW for predictable system initialization. Outputs of the PALCE610 depend on whether they are selected as registered or combinatorial. If registered is selected, the output will be LOW. If combinatorial is selected, the output will be a function of the logic. The Vcc rise must be monotonic and the reset delay time is 1000 ns maximum. Details on power-up reset can be found on page 17.

## **Register Preload**

The register on the PALCE610 can be preloaded from the output pins to facilitate functional testing of complex state machine designs. This feature allows direct loading of arbitrary states, making it unnecessary to cycle through long test vector sequences to reach a desired state. In addition, transitions from illegal states can be verified by loading illegal states and observing proper recovery.

## **Security Bit**

After programming and verification, a PALCE610 design can be secured by programming the security bit. Once programmed, this bit defeats readback of the internal programmed pattern by a device programmer, securing proprietary designs from competitors. However, programming and verification are also defeated by the security bit. The bit can only be erased in conjunction with the array during the erase cycle. Preload is not affected by the security bit.

## Technology

The PALCE610 is manufactured using AMD's advanced Electrically Erasable (EE) CMOS process. This technology uses an EE cell to replace the fuse link in bipolar parts, and allows AMD to offer lower-power parts of high complexity. In addition, since the EE cells can be erased and reprogrammed, these devices can be 100% factory tested before being shipped to the customer. Inputs and outputs are designed to be compatible with TTL devices. This technology provides strong input clamp diodes, output slew-rate control, and a grounded substrate for clear switching.

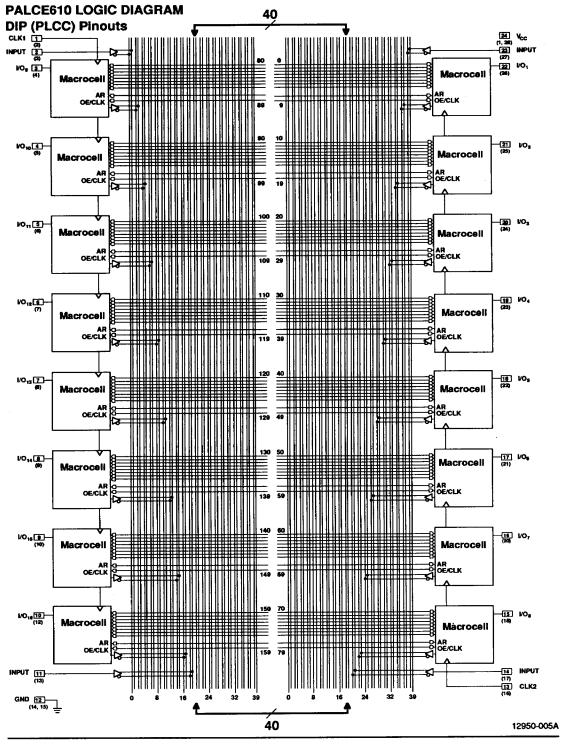
## **Programming and Erasing**

The PALCE610 can be programmed on standard logic programmers. Approved programmers are listed on page 18.

The PALCE610 may be erased to reset a previously configured device back to its virgin state. Bulk erase is automatically performed by the programming hardware. No special erase operation is required.

## **CMOS Compatibility**

The PALCE610 has CMOS-compatible outputs. The output voltage (Vo<sub>H</sub>) is 3.85 V at -2.0 mA.





## **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature

-65°C to +150°C

Ambient Temperature with Power Applied

-55°C to +125°C

Supply Voltage with

Respect to Ground

-0.5 V to +7.0 V

DC Input Voltage
DC Output or I/O Pin Voltage

-0.5 V to Vcc + 0.5 V

Static Discharge Voltage

-0.5 V to Vcc + 0.5 V 2001 V

**Latchup Current** 

(TA = 0°C to +75°C)

100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

## **OPERATING RANGES**

Commercial (C) Devices

Ambient Temperature (Ta)

Operating in Free Air

0°C to +75°C

Supply Voltage (Vcc)

with Respect to Ground

+4.75 V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified (Note 2)

Parameter Symbol	Parameter Description	Test Conditions		Min.	Max.	Unit
Vон	Output HIGH Voltage	VIN = VIH OF VIL VCC = Min.	I <sub>OH</sub> = -4.0 mA	2.4 3.84		V
Vol	Output LOW Voltage	VIN = VIH OF VIL Vcc = Min.	lo <sub>L</sub> = 8.0 mA	0.5.4	0.5 0.45	V V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)		2.0		>
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	٧
lн	Input HIGH Leakage Current	V <sub>IN</sub> = 5.25 V, V <sub>CC</sub> = Max. (Note 2)			10	μА
ĪιL	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max. (Note 2)			-10	μΑ
ЮZН	Off-State Output Leakage Current HIGH	V <sub>OUT</sub> = 5.25 V, V <sub>CC</sub> = Max. V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> (Note 2)			10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max. V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> (Note 2)			-10	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max. (Note 3)		-30	-150	mA
lcc	Supply Current	V <sub>IN</sub> = 0 V, Outputs Open (Ioυτ = 0 mA) Vcc = Max.			90	mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and lozL (or IIH and lozH).
- Not more than one output should be tested at a time. Duration of the short-circuit should not exceed one second. Vour = 0.5 V
  has been chosen to avoid test problems caused by tester ground degradation.

## **CAPACITANCE (Note 1)**

Parameter Symbol	Parameter Description	Test Condition	ens	Тур.	Unit
Cin	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V	8	
	0	14 0014	TA = +25°C	<u> </u>	pF
Cour	Output Capacitance	Vout = 2.0 V	f = 1 MHz	1 8	

#### Note:

## SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

				15	-25			
Parameter Symbol	Parameter D	escription		Min.	Max.	Min.	Max.	Unit
t <sub>PD</sub>	Input or Feed	lback to Combinatorial	Output		15		25	ns
ts	Setup Time f	rom Input or Feedback	to Clock	12		15		ns
tн	Hold Time			0		0		ns
tco	Clock to Outp	out			8		12	ns
tw.	Clock	LOW		6		10		ns
twн	Width	HIGH		6		10		ns
	Maximum	External Feedback	1/(ts + tco)	50		37		MHz
fmax	Frequency	Internal Feedback		76.1		40 .		MHz
	(Note 3)	No Feedback	1/(tw+ + twL)	83.3		50		MHz
<b>tea</b>	Input to Output Enable Using Product Term Control			15		25	ns	
ter	Input to Outp	ut Disable Using Produ	uct Term Control		15		25	ns
tar	Asynchronou	s Reset to Registered	Output		15		25	ns
tarw	Asynchronou	s Reset Width		10		15		ns
tarr	Asynchronou	s Reset Recovery Tim	e		15		25	ns
tsa	Setup Time f (Note 4)	rom Input or Feedback	to Clock	5		8		ns
tha	Hold Time (N	lote 4)		5		12		ns
tcoa	Clock to Outp	out (Note 4)			15		27	ns
twla	Clock	LOW (Note 4)		6		10		ns
TWHA	Width	HIGH (Note 4)		6		10		ns
	Maximum	External Feedback	1/(tsa + tcoa)	50		28.6		MHz
fmaxa	Frequency (Notes 3	Internal Feedback		61.6		29.4		MHz
	and 4)	No Feedback	1/(twla + twha)	83.3		50		MHz

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. These parameters are measured using the asynchronous product-term clock.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



#### **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature -65°C to +150°C

Ambient Temperature

with Power Applied

-55°C to +125°C

Supply Voltage with

Respect to Ground

-0.5 V to +7.0 V

DC Input Voltage -0.5 V to Vcc + 0.5 V

DC Output or I/O

Pin Voltage

-0.5 V to Vcc + 0.5 V

Static Discharge Voltage

2001 V

**Latchup Current** 

 $(T_C = -55^{\circ}C \text{ to } +125^{\circ}C)$ 

100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ. Absolute Maximum Ratings are for system design reference; parameters given are not tested.

## **OPERATING RANGES**

Military (M) Devices (Note 1)

Operating Case

Temperature (Tc)

-55°C to +125°C

Supply Voltage (Vcc)

with Respect to Ground

+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

#### Note:

 Military products are 100% tested at Tc = +25°C, +125°C and -55°C, per MIL-STD-883.

## DC CHARACTERISTICS over MILITARY operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions		Parameter Description Test Conditions		Max.	Unit
Vон	Output HIGH Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.4 3.84		٧		
Vol	Output LOW Voltage	IOL = 4 mA VIN = VIH OF VIL VCC = Min.		0.5	V		
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0		V		
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)		8.0	V		
lн	Input HIGH Leakage Current	V <sub>IN</sub> = 5.5 V, V <sub>CC</sub> - Max. (Note 4)		10	μΑ		
İIL	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V∞ - Max. (Note 4)		-10	μΑ		
ЮZН	Off-State Output Leakage Current HIGH	Vout = 5.5 V, Vcc - Max. Vin = Vih or Vil (Note 4)		10	μА		
lozı	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc - Max. Vin = Vin or Vil (Note 4)		-10	μΑ		
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = 5.0 V, Ta = 25° C (Note 5)	-30	-150	mA		
lcc	Supply Current	Outputs Open (louт= 0 A) Vcc = Max.		90	mA		

- 2. For APL products, Group A, Subgroups 1, 2 and 3 are tested per MIL-STD-833, Method 5005, unless otherwise noted.
- 3. VIL and VIH are input conditions of output tests and are not themselves directly tested. VIL and VIH are absolute voltages with respect to device ground and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.
- 4. VO pin leakage is the worst case of liL and lozL (or liH and lozH).
- 5. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vour = 0.5 V has been chosen to avoid test problems caused by tester ground degradation. This parameter is not 100% tested, but is evaluated at initial characterization and at anytime the design is modified where los may be affected.

## **CAPACITANCE (Note 1)**

Parameter Symbol	Parameter Description	Test Conditions		Тур.	Unit
Cin	Input Capacitance	VIN = 2.0 V	VCC T <sub>A</sub> = +25°C	8	ρF
Соит	Output Capacitance	Vout = 2.0 V	1	8	Pi

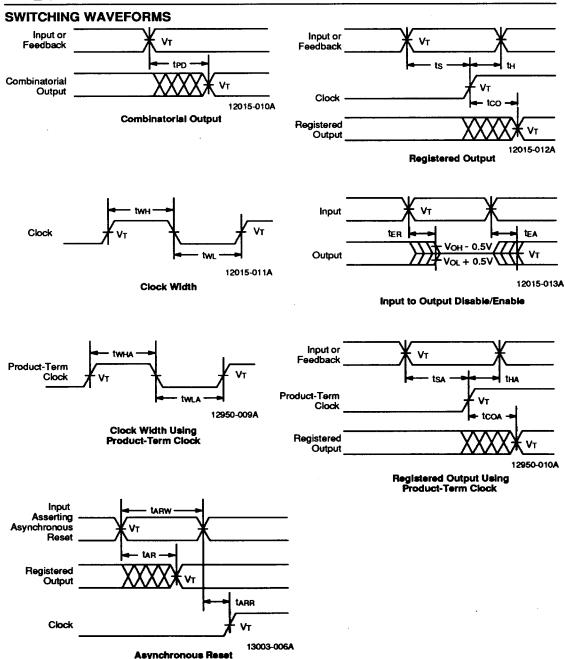
#### Note:

## **SWITCHING CHARACTERISTICS over MILITARY operating ranges (Note 2)**

					:0	
Parameter Symbol	Parameter D	Description		Min.	Max.	Unit
teo	Input or Feed	dback to Combinatorial	Output		20	ns
ts	Setup Time f	Setup Time from Input or Feedback to Clock				ns
tн	Hold Time			0		ns
tco	Clock to Out	put			10	ns
tw∟	Clock	LOW		8		ns
twн	Width	HIGH		8		ns
	Maximum	External Feedback	1/(ts + tco)	40		MHz
fmax	Frequency	Internal Feedback		50		MHz
	(Note 3)	No Feedback	1/(tw+ + twl)	62.5		MHz
tea	Input to Outp (Note 3)	Input to Output Enable Using Product Term Control (Note 3)			20	ns
ter	Input to Output Disable Using Product Term Control (Note 3)				20	ns
tar	Asynchronou	s Reset to Registered	Output		20	ns
larw	Asynchronou	s Reset Width (Note 3)	)	20		ns
tarr	Asynchronou	s Reset Recovery Tim	e (Note 3)		20	ns
tsa	Setup Time f (Note 4)	rom Input or Feedback	to Clock	8		ns
tha	Hold Time (N	lote 4)		10		ns
tcoa	Clock to Out	put (Note 4)			20	ns
twLA	Clock	LOW (Note 4)		8		ns
twha	Width	HIGH (Note 4)		8		ns
	Maximum	External Feedback	1/(tsa + tcoa)	35.8		MHz
fmàxa.	Frequency	Internal Feedback		45		MHz
	(Notes 3 and 4)	No Feedback	1/(twla + twha)	52.6		MHz

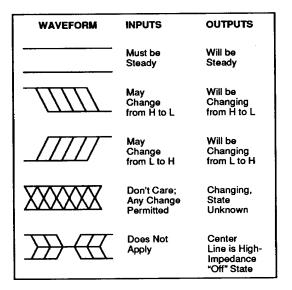
- See Switching Test Circuit for test conditions. For APL Products, Group A, Subgroups 9, 10, and 11 are tested per MIL-STD-883, Method 5005, unless otherwise noted.
- These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where frequency may be affected.
- 4. These parameters are measured using the asynchronous product-term clock.

These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



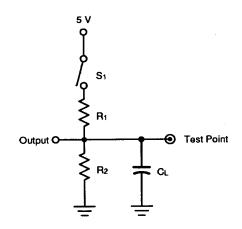
- 1. VT = 1.5 V
- 2. Input pulse amplitude 0 V to 3.0 V
- 3. Input rise and fall times 2-5 ns typical.

## **KEY TO SWITCHING WAVEFORMS**



KS000010-PAL

#### SWITCHING TEST CIRCUIT



12950-012A

Specification	S <sub>1</sub>	CL	Commercial		Military		Measured
			R <sub>1</sub>	R <sub>2</sub>	R <sub>1</sub>	R <sub>2</sub>	Output Value
tpo, tco	Closed	35 pF	855 Ω	340 Ω	855 Ω	340 Ω	1.5 V
tea .	Z → H : Open Z → L : Closed	35 pF	855 Ω	340 Ω	855 Ω	340 Ω	1.5 V
tея	H → Z : Open L → Z : Closed	5 pF	855 Ω	340 Ω	855 Ω	340 Ω	$H \rightarrow Z$ : V <sub>OH</sub> $- 0.5 V$ L $\rightarrow$ Z: V <sub>OL</sub> $+ 0.5 V$

#### **f**<sub>MAX</sub> Parameters

The parameter f<sub>MAX</sub> is the maximum clock rate at which the device is guaranteed to operate. Because flexibility inherent in programmable logic devices offers a choice of clocked flip-flop designs, f<sub>MAX</sub> is specified for three types of synchronous designs.

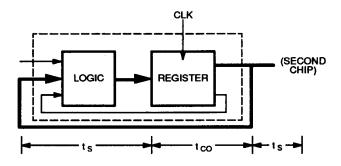
The first type of design is a state machine with feedback signals sent off-chip. This external feedback could go back to the device inputs, or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals (ts + tco). The reciprocal, f<sub>MAX</sub>, is the maximum frequency with external feedback or in conjunction with an equivalent speed device. This f<sub>MAX</sub> is designated "f<sub>MAX</sub> external."

The second type of design is a single-chip state machine with internal feedback only. In this case, flip-flop outputs are defined by the device inputs and flip-flop inputs. Under these conditions, the period is limited by

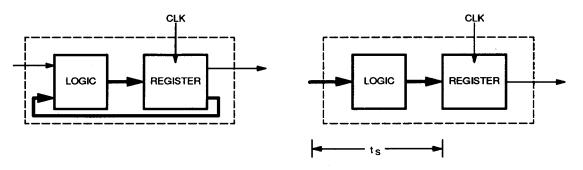
the internal delay from the flip-flop outputs through the internal feedback and logic to the flip-flop inputs. This f<sub>MAX</sub> is designated "f<sub>MAX</sub> internal".

The third type of design is a simple data path application. In this case, input data is presented to the flip-flop and clocked through; no feedback is employed. Under these conditions, the period is limited by the sum of the data setup time and the data hold time ( $t_s+t_H$ ). However, a lower limit for the period of each  $f_{MAX}$  type is the minimum clock period ( $t_{WH}+t_{WL}$ ). Usually, this minimum clock period designates the period for the third  $f_{MAX}$ , designated " $f_{MAX}$  no feedback)."

fmax external and fmax no feedback are calculated. fmax external is calculated from ts and tco, and fmax no feedback is calculated from tw. and twn. fmax internal is measured. This discussion also applies for asynchronous operation. The only difference is the fact that the clock signal passes through the array.



fMax External Feedback; 1/(ts + tco)



fmax Internal Feedback

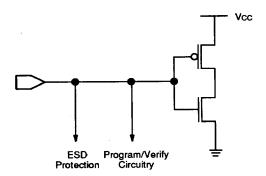
fmax No Feedback; 1/(ts + th) or 1/(twh + twl)

12015-020A

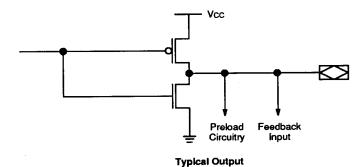
## **ENDURANCE**

Symbol	Parameter Description	Test Conditions	Min.	Unit
ton	Pattern Data Retention Time	Max. Storage Temperature	10	Years
		Max. Operating Temperature	20	Years
N	Reprogramming Cycles	Normal Programming Conditions	100	Cycles

# INPUT/OUTPUT EQUIVALENT SCHEMATICS



**Typical Input** 



12950-011A



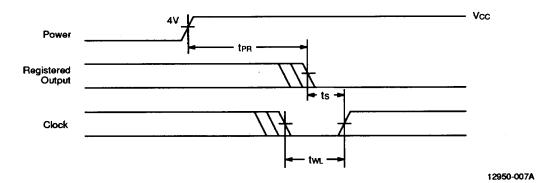
## **Power-Up Reset**

The power-up reset feature ensures that all flip-flops will be reset to LOW after the device has been powered up. This feature is valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and wide range of ways Vcc can rise to

its steady state, two conditions are required to insure a valid power-up reset. These conditions are:

- 1. The Vcc rise must be monotonic.
- Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Description	Max.	Unit
ten	Power-up Reset Time	. 1000	ns
ts	Input or Feedback Setup Time	See Switching	
twL	Clock Width LOW	Characteristics	



**Power-Up Reset Waveform** 



# APPROVED PROGRAMMERS (subject to change)

MANUFACTURER	PROGRAMMER CONFIGURATION			
Advanced Micro Devices, Inc. 901 Thompson Place MS 1028 Sunnyvale, CA 94088-3543 (800) 222-9323 or (408) 732-2400	LabPro™ Rev. 1.2			
BP Microsystems 10881 Haddington Suite #190 Houston, TX 77043 (800) 225-2102 or (713) 461-9430	CP-1128 Rev. 1.47F			
Data VO Corporation 10525 Willows Road N.E. P.O. Box 97046 Redmond, WA 98073-9746 (800) 247-5700 or (206) 881-6444	System 29A, 29B Family/Pinout Codes  LogicPak™ 303A-V04 80–59  Adapter 303A-011A-V13 (DIP)  UniSite™ Rev. 3.0 (DIP)  UniOdel 2900 Rev. 1.3			
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JMC Hakusan High-Tech Park 807-I Hakusan-Cho Midori-Ku Yokohama-City 226, Japan 045-939-6150	Contact Manufacturer			
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Sprint Expert International, Inc. 13720 Midway, Suite 105 Dallas, TX 75244 (214) 980-2896 or Vanderweydendreef 27 1900 Overijse, Belgium 2-687-4154	Sprint-Plus Rev. 3.40			
Stag Microsystems Inc. 1600 Wyatt Dr. Suite 3 Santa Clara, CA 95054 (408) 988-1118 or Stag House Martinfield, Welwyn Garden City Herfordshire UK AL7 1JT 707-332148	Contact Manufacturer			
Systems General 244 Hillview Dr. Milpitas, CA 95035 (408) 263-6667 or 3F, No. 6, Lane 4, Tun Hwa N. Rd. Taipei, Taiwan 2-721-2613	Contact Manufacturer			

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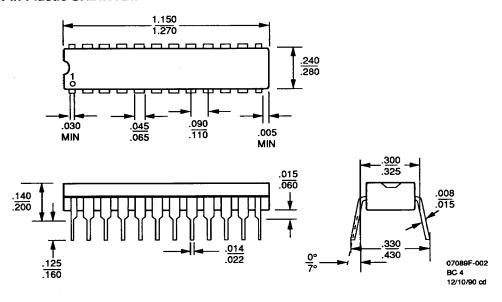
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ISDATA GmbH Haid-und-Neu-Str. 7 D-7500 Karlsruhe 1, West Germany 0721/69 30 92	LOG/iC™ Software, rev. 3.1 or later		
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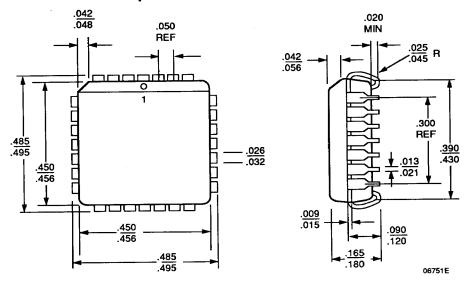
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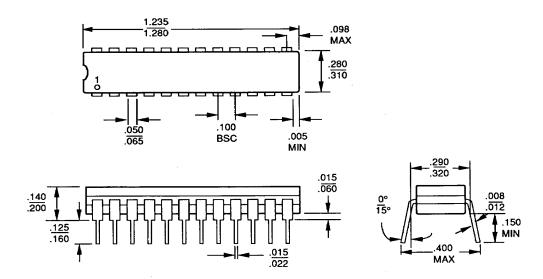
## PHYSICAL DIMENSIONS\* PD3024 24-Pin Plastic SKINNYDIP



PL 028 28-Pin Plastic Leaded Chip Carrier

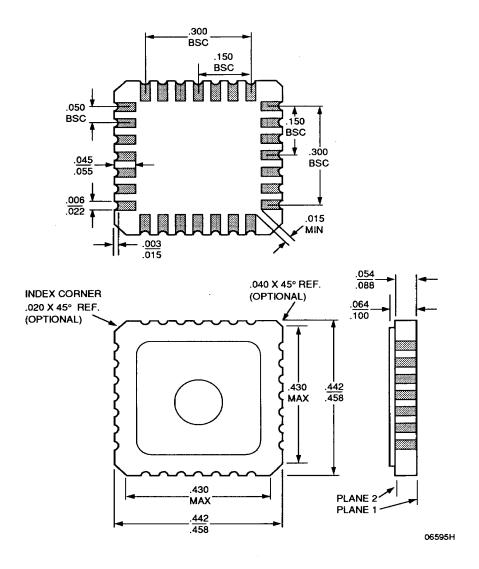


#### PHYSICAL DIMENSIONS\* CD3024 Ceramic SKINNYDIP



06850C

## PHYSICAL DIMENSIONS\* CL 028 Ceramic Leadless Chip Carrier



\*For reference only. All dimensions measured in inches. BSI is an ANSI standard for Basic Space Centering.

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